



Customer Information Notification

202311003I : NBP8/9 Product Family Datasheet Update

Note: This notice is NXP Company Proprietary.

Issue Date: Nov 03, 2023 **Effective date:** Nov 04, 2023

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Management summary

Update of datasheet for NBP8/9 product family (Revision 3.1; Sept 13, 2023) in Section 10.2 Media Compatibility.

Change Category

<input type="checkbox"/> Wafer Fab Process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Test Process	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Location	<input type="checkbox"/> Electrical spec./Test coverage
<input type="checkbox"/> Firmware <input checked="" type="checkbox"/> Other				

PCN Overview

Description

Update of datasheet for NBP8/9 product family (Revision 3.1; Sept 13, 2023) in Section 10.2 Media Compatibility.

Reason

Added new note as follows:

The devices contain a gel that protects the pressure transducer and its inter-die connection wires from corrosion, which might otherwise result in catastrophic failure modes. NXP has observed that direct exposure to materials with the same or nearly-the-same solubility can potentially result in a corruption of the protective gel. A corruption can be less than catastrophic in nature, however may result in an offset of the pressure measurement from its factory calibrated value. An offset can potentially be larger than the allowed tolerances published in this data sheet.

Further, NXP does not recommend direct exposure to strong acid or strong base compounds as they can potentially result in a similar corruption as described above, or may result in a dissolution of the protective gel and/or the metal lid adhesive and/or the plastic device body. Such a dissolution can be catastrophic in nature, damaging the transducer surfaces and/or internal wire bonds and/or the control die surfaces. A potential dissolution may result in a similar offset, or cause the device to indicate overflow/underflow status, or may cause the device to cease operating in the worst case.

For a list of compounds known to generate out-of-tolerance offsets and/or catastrophic device failure, please contact an NXP sales representative.

Identification of Affected Products

Product identification does not change

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Data Sheet Revision

A new datasheet will be issued

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Additional documents: [view online](#)

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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NXP Quality Management Team.

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Orderable Part Number#	12NC	Product Type	Product Description	Package Outline	Package Description	Product Status	Customer Specific Indicator	Product Line
NBP8FD4T1	935408776528	NBP8FD4T1	BPMS 40 - 250kPa	HQFN24FAMWF	SOT1931-1(D)	DOD	No	BLC6
NBP9FD4T1	935410617528	NBP9FD4T1	BPMS SPI PWM	HQFN24FAMWF	SOT1931-1(D)	DOD	No	BLC6